

THERMAL PAD - DT12

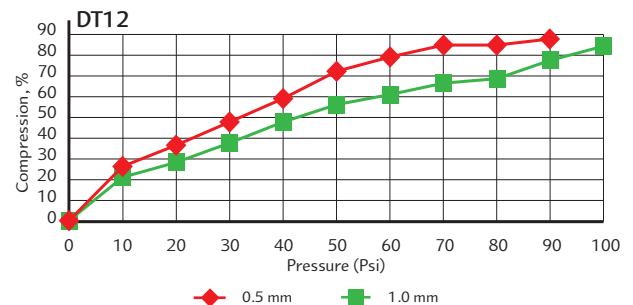
Features

- Thermal conductivity: 1.2 W/mK
- High conformability
- Cost effective solution
- Electrically insulating
- Naturally sticky
- High dielectric breakdown of up to 6.5 kV/mm
- Custom die-cut parts: custom configurations available



Applications

- Between electronic components: semiconductors, ICs, CPUs, MOS and heatsink
- LEDs, LCD TV, telecom devices, wireless hubs, PCs, power supply etc.
- Cooling and thermal modules
- In all applications where a metal housing is used as heatsink.



Part number code (example):

UDT 10/H10 - T 10

- Thickness: 1.0 mm
- Hardness: 10 Shore C
- Thermal Conductivity: 1.0 W/mK
- UDT: Thermal Pad

TECNITE DT12

Properties	Unit	DT12	Test Method
Composition		Silicone & ceramic filled	
Colour		Pink	
Thickness range	mm	0.5 -12.0	
Hardness	Shore C	15	ASTM D2240
Density	g/ml	2.3	ASTM D792
Elongation	%	70	ASTM D412
Temperature range	°C	-40 to 150	EN344
Breakdown voltage	kV/mm	≥6.5	ASTM D149
Volume impedance	ohm*cm	3.5*10 ¹²	ASTM D257
Dielectric constant	@ 1 MHz	3.87	ASTM D150
Weight dampify	%	≥1	@ 150 °C 240H
Thermal conductivity	W/mK	1.2	ASTM E1461
Thermal Resistance @ 40 psi	°C-in ² /W	1.118 @ 1.0 mm	
Compliances		UL 94 V-0, RoHS, REACH	
Sheet sizes		Standard: 200*400 mm	
Custom configurations		Custom die-cut parts available. Available with acrylic PSA tape for improved application on one or both sides: • 3M Double Coated Tape 9448HK (will make the pad 0.15 mm thicker on both sides) • 3M 3M467 Transfer Tape (will make the pad 0.06 mm thicker on both sides)	

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